

20V N-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY V(BR)DSS=20V; RDS(ON)=0.015Ω; ID=9A

DESCRIPTION

This new generation of high density MOSFETs from Zetex utilises a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.

FEATURES

- Low on-resistance
- Fast switching speed
- Low threshold
- · Low gate drive
- Low profile SOIC package

APPLICATIONS

- DC DC Converters
- Power Management Functions
- Disconnect switches
- Motor control

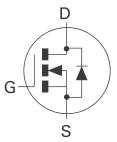
ORDERING INFORMATION

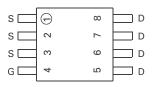
DEVICE	REEL SIZE (inches)	TAPE WIDTH (mm)	QUANTITY PER REEL
ZXM66N02N8TA	13	12mm embossed	1000 units

DEVICE MARKING

ZXM6 6N02







Top View



ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V _{DSS}	20	V	
Gate- Source Voltage	V _{GS}	±12	V	
Continuous Drain Current (V_{GS} =4.5V; T_A =25°C)(b)(d) (V_{GS} =4.5V; T_A =70°C)(b)(d)	I _D	9.0 8.0	А	
Pulsed Drain Current (c)(d)	I _{DM}	35	A	
Continuous Source Current (Body Diode)(b)(d)	I _s	3.1	A	
Pulsed Source Current (Body Diode)(c)(d)	I _{SM}	35	A	
Power Dissipation at $T_A=25^{\circ}C$ (a)(d) Linear Derating Factor	P _D	-	W mW/°C	
Power Dissipation at T _A =25°C (a)(e) Linear Derating Factor	P _D		W mW/°C	
Power Dissipation at T _A =25°C (b)(d) Linear Derating Factor	P _D	2.5 20	W mW/°C	
Operating and Storage Temperature Range	T _j :T _{stg}	-55 to +150	°C	

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{_{ hetaJ}A}$	-	°C/W
Junction to Ambient (b)	$R_{_{ hetaJ}A}$	30	°C/W

NOTES

(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

(b) For a device surface mounted on FR4 PCB measured at t ${\leqslant}10$ secs.

(c) Repetitive rating - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.



ELECTRICAL	CHARACTERISTICS	(at T _{amb} = 25°C	unless otherwise stated).
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PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNI T	CONDITIONS.	
STATIC	•						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	20			V	I _D =250μA, V _{GS} =0V	
Zero Gate Voltage Drain Current	I _{DSS}			1	μA	V _{DS} =16V, V _{GS} =0V	
Gate-Body Leakage	I _{GSS}			100	nA	$V_{GS}=\pm 12V, V_{DS}=0V$	
Gate-Source Threshold Voltage	V _{GS(th)}	0.7			V	$I_{D} = 250 \mu A, V_{DS} = V_{GS}$	
Static Drain-Source On-State Resistance (1)	R _{DS(on)}			0.015 0.020	Ω Ω	V _{GS} =4.5V, I _D =4.1A V _{GS} =2.5V, I _D =3.5A	
Forward Transconductance (3)	9 _{fs}	11			s	V _{DS} =15V,I _D =4.1A	
DYNAMIC (3)	•					•	
Input Capacitance	C _{iss}		-		pF	V _{DS} =15 V, V _{GS} =0V, f=1MHz	
Output Capacitance	C _{oss}		-		pF		
Reverse Transfer Capacitance	C _{rss}		-		pF		
SWITCHING(2) (3)							
Turn-On Delay Time	t _{d(on)}		-		ns		
Rise Time	t _r		-		ns	$V_{DD} = 10V$, $I_D = 4.1A$ $R_G = 6.0\Omega$, $R_D = 2.4\Omega$ (Refer to test circuit)	
Turn-Off Delay Time	t _{d(off)}		-		ns		
Fall Time	t _f		-		ns		
Total Gate Charge	Q _g			-	nC		
Gate-Source Charge	Q _{gs}			-	nC	$V_{DS} = 16V, V_{GS} = 4.5V$ $I_{D} = 4.1A$	
Gate Drain Charge	Q _{gd}			-	nC	(Refer to test circuit)	
SOURCE-DRAIN DIODE						•	
Diode Forward Voltage (1)	V _{SD}			0.95	V	T _j =25°C, I _S =4.1A, V _{GS} =0V	
Reverse Recovery Time (3)	t _{rr}		-		ns	T _j =25°C, I _F =4.1A, di/dt= 100A/μs	
Reverse Recovery Charge(3)	Q _{rr}		-		nC		

(1) Measured under pulsed conditions. Width=300 $\mu s.$ Duty cycle ${\leq}2\%$.

(2) Switching characteristics are independent of operating junction temperature.

(3) For design aid only, not subject to production testing.





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